

IN THE CLAIMS

Please cancel claims 55-58, 60-63, and 65-67 without prejudice.

Please amend claims 54, 59, and 64.

Please add new claims 68-79.

Please enter the following pending claims:

54. (Currently Amended) A polish pad comprising:

~~a pad center area, said pad center area corresponding to a wafer center area;~~
~~a first set of grooves disposed in said pad center a first area, said first set of~~
~~grooves having a first depth;~~
~~a pad edge area disposed adjacent to said pad center area, said pad edge area~~
~~corresponding to a wafer edge area; and~~
~~a second set of grooves disposed in said pad edge a second area, said second~~
~~set of grooves having a second depth, wherein said first depth is smaller than said~~
~~second depth to reduce polish rate in said first area.~~

55.-58. (Canceled)

59. (Currently Amended) A polish pad comprising:

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~~a pad center area, said pad center area corresponding to a wafer center area;~~
~~a first set of grooves disposed in said pad center a first area, said first set of~~
~~grooves having a first width;~~

~~a pad edge area disposed adjacent to said pad center area, said pad edge area~~
~~corresponding to a wafer edge area; and~~

~~a second set of grooves disposed in said pad edge a second area, said second~~
~~set of grooves having a second width, wherein said first width is smaller than said~~
~~second width to reduce polish rate in said first area.~~

60.-63. (Canceled)

64. (Currently Amended) A polish pad comprising:

~~a pad center area, said pad center area corresponding to a wafer center area;~~
~~a first set of grooves disposed in said pad center a first area, said first set of~~
~~grooves having a first density;~~

~~a pad edge area disposed adjacent to said pad center area, said pad edge area~~
~~corresponding to a wafer edge area; and~~

~~a second set of grooves disposed in said pad edge a second area, said second~~
~~set of grooves having a second density, wherein said first density is smaller than~~
~~said second density to reduce polish rate in said first area.~~

65.-67. (Canceled)

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68. (New) The polish pad of claim 54 wherein said first area corresponds to a center
of a wafer to be polished on said polish pad.

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69. (New) The polish pad of claim 54 wherein said first area corresponds to edges of a wafer to be polished on said polish pad.

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70. (New) The polish pad of claim 54 wherein said first area is disposed in a center of said polish pad.

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71. (New) The polish pad of claim 54 wherein said first area is disposed at edges of said polish pad.

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72. (New) The polish pad of claim 59 wherein said first area corresponds to a center of a wafer to be polished on said polish pad.

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73. (New) The polish pad of claim 59 wherein said first area corresponds to edges of a wafer to be polished on said polish pad.

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74. (New) The polish pad of claim 59 wherein said first area is disposed in a center of said polish pad.

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75. (New) The polish pad of claim 59 wherein said first area is disposed at edges of said polish pad.

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76. (New) The polish pad of claim 64 wherein said first area corresponds to a center of a wafer to be polished on said polish pad.

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77. (New) The polish pad of claim 64 wherein said first area corresponds to edges of a wafer to be polished on said polish pad.

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78. (New) The polish pad of claim 64 wherein said first area is disposed in a center of said polish pad.

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79. (New) The polish pad of claim 64 wherein said first area is disposed at edges of said polish pad.